Printing Equipment for Printed Electronics 2015-2025

Description: This unique report addresses the applications and technologies of printing, curing and key integration equipment that is enabling printed electronics. The report assesses the performance of each printing and curing technology type, providing for each:

- Assessment of capability and suitability to printing different types of materials
- Analysis of existing uses of the printing technology in printed electronics
- Trends and opportunities for the printing technologies
- Leading suppliers and company profiles

This is assessed for the following printing and printed related manufacturing technologies:

- Screen printing
- Inkjet printing
- Flexo printing (and offset)
- Gravure printing (and offset)
- Nano imprinting/embossing
- Transfer printing
- Coating systems (Slot die and alternatives)

The following post-printing processes are also covered, including:

- Thermal drying
- IR and UV curing
- Photonic curing

In addition, we cover companies working on equipment integration, manufacturing centers and government funded printed electronics initiatives and manufacturing centers.

STATE OF MARKET AND FUTURE APPLICATION ASSESSMENT

The report looks at the current deployment of printing technologies by type and by application, summarized as follows:

Each printing type is assessed versus emerging products - covering which materials are suitable to each printing type and the application potential for those printed devices. Often, printing is only part of the complete product, and therefore we address printing electronic or electrical materials by layer type.

89 organizations covered
Progress of 89 organizations are covered, segmented by products they provide, value chain positioning and the market leaders are identified.

WHO SHOULD BUY THIS REPORT

- Ink developer and suppliers
- Manufactures (screen printers, inkjet printers, etc)

Those active in the value chain for developing:
- ITO replacements
- Photovoltaics
- RFID
- Photovoltaics
- Logic and memory
- Interactive or smart packaging
1. EXECUTIVE SUMMARY AND CONCLUSIONS
1.1. Comparison of Printing Technologies
1.1.1. Output performance comparison
1.1.2. Running performance comparison
1.1.3. Printing Type by Application
1.1.4. Value chain for equipment for printed electronics
1.1.5. Profitability
1.1.6. Opportunities - Component Attach
1.2. Forecasts by printing equipment type vs component 2015-2025
1.3. Printed Electronics Equipment Sales: Companies Look to Asia
1.3.1. Europe Government Funding for Equipment Declines

2. INTRODUCTION
2.1. What is printed electronics
2.2. Why printing?
2.3. Types of Printed electronics technologies/components
2.4. Market size of printed electronics 2015-2025
2.5. Printing Technologies

3. PRINTED ELECTRONICS MARKET
3.1. Crystalline Silicon Photovoltaics
3.2. Thin Film Photovoltaics
3.3. Touch screens
3.4. Logic and memory
3.5. OLED displays and lighting
3.6. Smart Packaging
3.7. Transparent Conductive Films
3.8. Direct Printing

4. SCREEN PRINTING
4.1. Introduction
4.2. Screen printing forecasts 2015-2025
4.3. Suitability to different devices/ components
4.4. Existing uses
4.5. Future uses
4.6. Innovation and technical progress
4.6.1. Resolution
4.6.2. Print on print (Double print)
4.7. Company profiles
4.7.1. A&M Kinzel Siebdruckmaschinen Ltd
4.7.2. Applied Materials Baccini
4.7.3. Asada Mesh
4.7.4. DEK Printing Machines Ltd
4.7.5. Dynamesh
4.7.6. Ever Bright Printing Machine Fty. Ltd
4.7.7. KIWO
4.7.8. Metal Etch Services Inc
4.7.9. p-tec GmbH
4.7.10. Saati Americas Corp
4.7.11. Sefar
4.7.12. Spartanics
4.7.13. SPGprints
4.7.14. Thieme Corporation
4.7.15. Thieme GmbH & Co KG
4.7.16. Ulano
4.7.17. UTZ Technologies
4.7.18. Werner Kammann Maschinenfabrik GmbH & Co. KG

5. INKJET PRINTING
5.1. Introduction
5.2. Inkjet printing forecasts 2015-2025
5.3. Suitability to different devices/ components
5.4. Existing uses
5.5. Future uses
5.5.1. Printed interconnects
5.5.2. Mass customization
5.5.3. OLED and flat panel displays, OLED lighting, Touch screens, OPV
5.5.4. Touch panel bezels
5.5.5. Masking followed by plating
5.5.6. PV bus bars and fingers
5.6. Company profiles
5.6.1. Ceradrop
5.6.2. Fujifilm Dimatix
5.6.3. Kateeva
5.6.4. Meyer Burger PixDro
5.6.5. Optomec
5.6.6. Samsung Electro-Mechanics
5.6.7. SCHMID Group
5.6.8. Seiko Epson
5.6.9. Sij Technology
5.6.10. Sonoplot
5.6.11. THG Inkjet
5.6.12. Unijet
5.6.13. Xaar

6. FLEXO PRINTING
6.1. Introduction
6.2. Flexo printing forecasts 2015-2025
6.3. Suitability to different devices/ components
6.4. Existing uses
6.5. Future uses
6.6. Company profiles
6.6.1. Gallus
6.6.2. Harper Corporation
6.6.3. Mark Andy
6.6.4. Multi Print Systems (MPS)
6.6.5. Nilpeter
6.6.6. Omet Varyflex

7. GRAVURE PRINTING
7.1. Introduction
7.2. Gravure printing forecasts 2015-2025
7.3. Suitability to different devices/ components
7.4. Existing uses
7.5. Future uses
7.6. Company profiles
7.6.1. Bobst Group
7.6.2. Chestnut Engineering
7.6.3. Comco
7.6.4. Harper Corporation
7.6.5. Komori
7.6.6. Mirwec Film
7.6.7. Nilpeter
7.6.8. Ohio Gravure Technologies Accupress

8. OTHER PRINTING TYPES
8.1. Other printing forecasts 2015-2025
8.2. Nano imprinting/embossing
8.2.1. Target applications
8.2.2. PragmatiC Printing
8.2.3. TNO
8.3. Transfer printing
8.3.1. Target applications
8.3.2. Semprius

9. COATING SYSTEMS: SLOT DIE AND ALTERNATIVES
9.1. Coating systems
9.2. Target Applications
9.3. Company profiles
9.3.1. Coatema
9.3.2. MegTec
9.3.3. Mitsubishi Materials Corporation
9.3.4. Ntact

10. POST PRINTING PROCESSING
10.1. Thermal drying
10.2. IR and UV curing
10.3. Photonic curing
10.4. Company profiles
10.4.1. Adphos
10.4.2. Heraeus Noblelight
10.4.3. Novacentrix
10.4.4. Xenon Corporation

11. EQUIPMENT INTEGRATION, HANDLING
11.1. Company profiles
11.1.1. 3D Micromac
11.1.2. Aixtron
11.1.3. Applied Laser Engineering ALE
11.1.4. Beneq
11.1.5. Bosch Rexroth
11.1.6. DP Patterning
11.1.7. InkTec
11.1.8. Kimoto Tech
11.1.9. Kroenert
11.1.10. Martin Automatic
11.1.11. Mekoprint A/S
11.1.12. Nordson Asymtek
11.1.13. Northfield Automation Systems
11.1.14. Notion Systems
11.1.15. Owens Design
11.1.16. Rolith, Inc.
11.1.17. Sempa Systems GmbH
11.1.18. Soligie
11.1.19. TDK-Lambda
11.1.20. Teknek Ltd.
11.1.21. VDL FLOW
11.1.22. Von Ardenne
11.1.23. Vinci Technologies
11.1.24. Werner Kammann Maschinenfabrik GmbH & Co. KG
11.1.25. Xymox

12. GOVERNMENT FUNDED CENTERS
12.1. Center profiles
12.1.1. Acreo, Sweden
12.1.2. CEA, France
12.1.3. Cetemmsa, Spain
12.1.4. CPI, UK
12.1.5. CSEM, Switzerland
12.1.6. Flexible Display Center, Arizona, USA
12.1.7. Holst Center (TNO, IMEC, Dutch Ministry of Economy Affairs, Government of Flanders), The Netherlands
12.1.8. ITRI, Taiwan
12.1.9. NRC
12.1.10. Printable Electronics Research Center, China
12.1.11. The Thailand Organic and Printed Electronics Center (TOPIC), Thailand
12.1.12. VTT
Ordering:

Order Online - [http://www.researchandmarkets.com/reports/3047539/](http://www.researchandmarkets.com/reports/3047539/)

Order by Fax - using the form below

Order by Post - print the order form below and send to

Research and Markets,
Guinness Centre,
Taylors Lane,
Dublin 8,
Ireland.
Fax Order Form
To place an order via fax simply print this form, fill in the information below and fax the completed form to 646-607-1907 (from USA) or +353-1-481-1716 (from Rest of World). If you have any questions please visit http://www.researchandmarkets.com/contact/

Order Information
Please verify that the product information is correct and select the format(s) you require.

Product Name: Printing Equipment for Printed Electronics 2015-2025
Web Address: http://www.researchandmarkets.com/reports/3047539/
Office Code: SCDK3XG8

Product Formats
Please select the product formats and quantity you require:

<table>
<thead>
<tr>
<th>Format</th>
<th>Quantity</th>
<th>Price</th>
</tr>
</thead>
<tbody>
<tr>
<td>Electronic (PDF) - 1 - 5 Users:</td>
<td>[ ]</td>
<td>USD 4876</td>
</tr>
<tr>
<td>Electronic and Hard Copy (PDF) - 1 - 5 Users:</td>
<td>[ ]</td>
<td>USD 5168 + USD 58 Shipping/Handling</td>
</tr>
<tr>
<td>Electronic (PDF) - 1 - 10 Users:</td>
<td>[ ]</td>
<td>USD 7299</td>
</tr>
<tr>
<td>Electronic and Hard Copy (PDF) - 1 - 10 Users:</td>
<td>[ ]</td>
<td>USD 7591 + USD 58 Shipping/Handling</td>
</tr>
</tbody>
</table>

* Shipping/Handling is only charged once per order.

Contact Information
Please enter all the information below in BLOCK CAPITALS

Title: [Mr] [Mrs] [Dr] [Miss] [Ms] [Prof]
First Name: ______________________ Last Name: ______________________
Email Address: ______________________
Job Title: ______________________
Organisation: ______________________
Address: ______________________
City: ______________________
Postal / Zip Code: ______________________
Country: ______________________
Phone Number: ______________________
Fax Number: ______________________

* Please refrain from using free email accounts when ordering (e.g. Yahoo, Hotmail, AOL)
Payment Information

Please indicate the payment method you would like to use by selecting the appropriate box.

☐ Pay by credit card: You will receive an email with a link to a secure webpage to enter your credit card details.

☐ Pay by check: Please post the check, accompanied by this form, to:
Research and Markets,
Guinness Center,
Taylors Lane,
Dublin 8,
Ireland.

☐ Pay by wire transfer: Please transfer funds to:
Account number 833 130 83
Sort code 98-53-30
Swift code ULSBIE2D
IBAN number IE78ULSB98533083313083
Bank Address Ulster Bank,
27-35 Main Street,
Blackrock,
Co. Dublin,
Ireland.

If you have a Marketing Code please enter it below:

Marketing Code: 

Please note that by ordering from Research and Markets you are agreeing to our Terms and Conditions at http://www.researchandmarkets.com/info/terms.asp

Please fax this form to:
(646) 607-1907 or (646) 964-6609 - From USA
+353-1-481-1716 or +353-1-653-1571 - From Rest of World